

Full Wafer & Singulated Die / Module High Volume Test and Reliability Verification Solution for Power, Photonics, Logic & Memory Devices



SYSTEM BENEFITS

- **High Throughput Reliability Verification and Test System for Volume Production**
 - ◆ Handles full wafers / panels / singulated die / modules for highest production throughput
 - ◆ Identifies failing logic / memory / photonic die before final package integration
 - ◆ Up to 18 Blades (slots) for wafer or panel testing using WaferPakTM contactors or 9 Blade capability for wafers / singulated die / module DiePak[®] carriers
 - ◆ Advanced high-power testing capability with up to 3,500 watts of power per wafer
- **Configurable Channel Resources**
 - ◆ Up to 4 modules available per Blade in 18 blade, or 8 modules in 9 blade configuration:
 - Universal Channel Modules (UCCM) with up to 2,048 resources (I/O / Clock / PPMU / DPS) per Blade with deep scan, pattern data and capture memory for testing of devices with BIST/DFT capabilities
 - High Voltage Power Channel Modules (HVPCM) with up to 1,024 29V channels
 - High Current Channel Modules (HCCM) with up to 1,024 2A channels
 - BiPolar Voltage Channel Modules (BVCM) with up to 1,024 channels from -30V to 40V
 - Very High Voltage Channel Modules (VHVCM) single channel up to 2,000V
- **Production Proven Full-Wafer Reliability Verification & Test Solution**
 - ◆ Reduces test costs by functionally testing wafers/die/modules during reliability verification
 - ◆ Offers a total solution when configured with a WaferPak contactor / DiePak carrier and Wafer Aligner / DiePak Loader
 - ◆ Protects devices with individual per channel over-current and over-voltage protection

“Setting the Test Standard for Tomorrow”

CORPORATE HEADQUARTERS

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